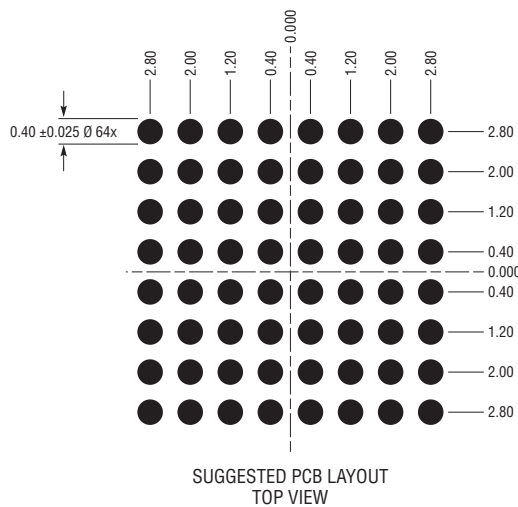
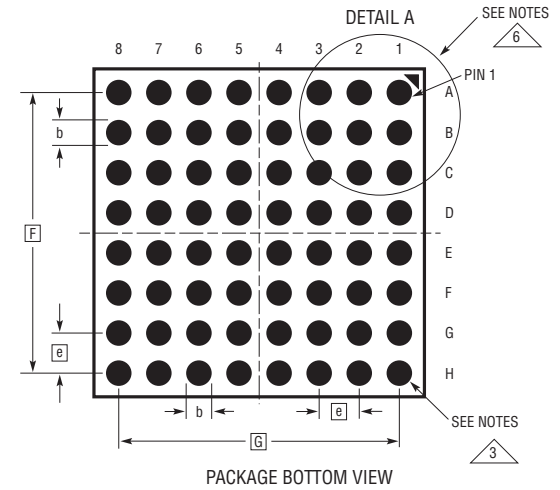
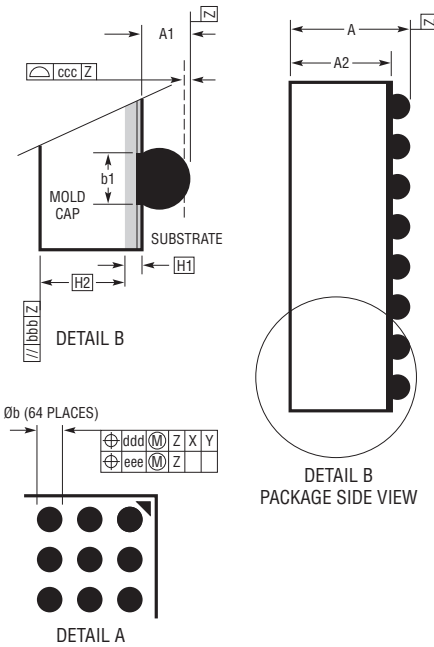
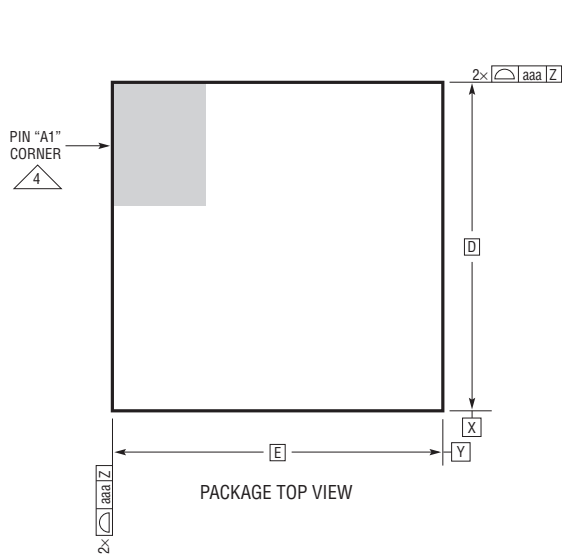


BGA Package
64-Lead (7.00mm × 7.00mm × 1.34mm)
 (Reference LTC DWG # 05-08-1587 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.15	1.34	1.53	
A1	0.30	0.40	0.50	BALL HT
A2	0.85	0.94	1.03	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		7.00		
E		7.00		
e		0.80		
F		5.60		
G		5.60		
H1		0.24		SUBSTRATE THK
H2		0.70		MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 64

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JEP95
 4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

